

In the Specification:

Please amend the specification as follows:

Page 8, third paragraph:

After the solder tip 21 has been preheated to the preselected temperature and the active ~~tip~~ tip 26 has been coated with solder, the solder head is moved with the aid of the linear modules 13 and 14 to the preselected position for the first pre-soldering. The solder tip 21 is lowered to the level that brings the active tip 26 into contact with the end, 5 or 6, of the capacitor element, whereby the contact pressure is determined by the level and the suspension of the contact head: partially floating, fixed, or floating with spring.